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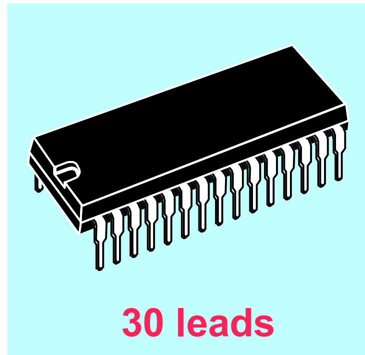
SDIP 30



PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.25 mm	2.61 W/cm°C
die attach	epoxy glue (silver filler)	10-40 µm	0.01 W/cm°C
molding compound	epoxy resin	3.8 mm	0.0063W/cm°C

Charts enclosed :

1) Rth(j-a) vs power dissipation
2) Zth(j-a) vs time

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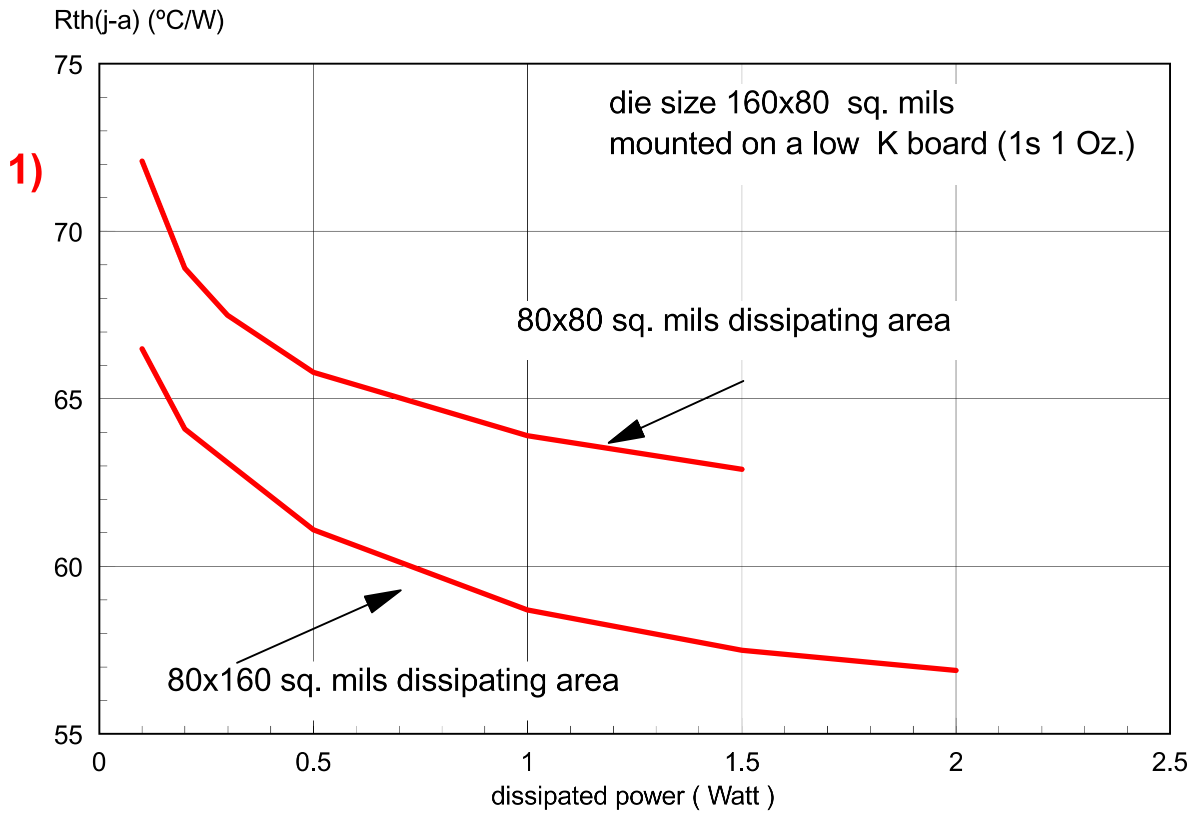
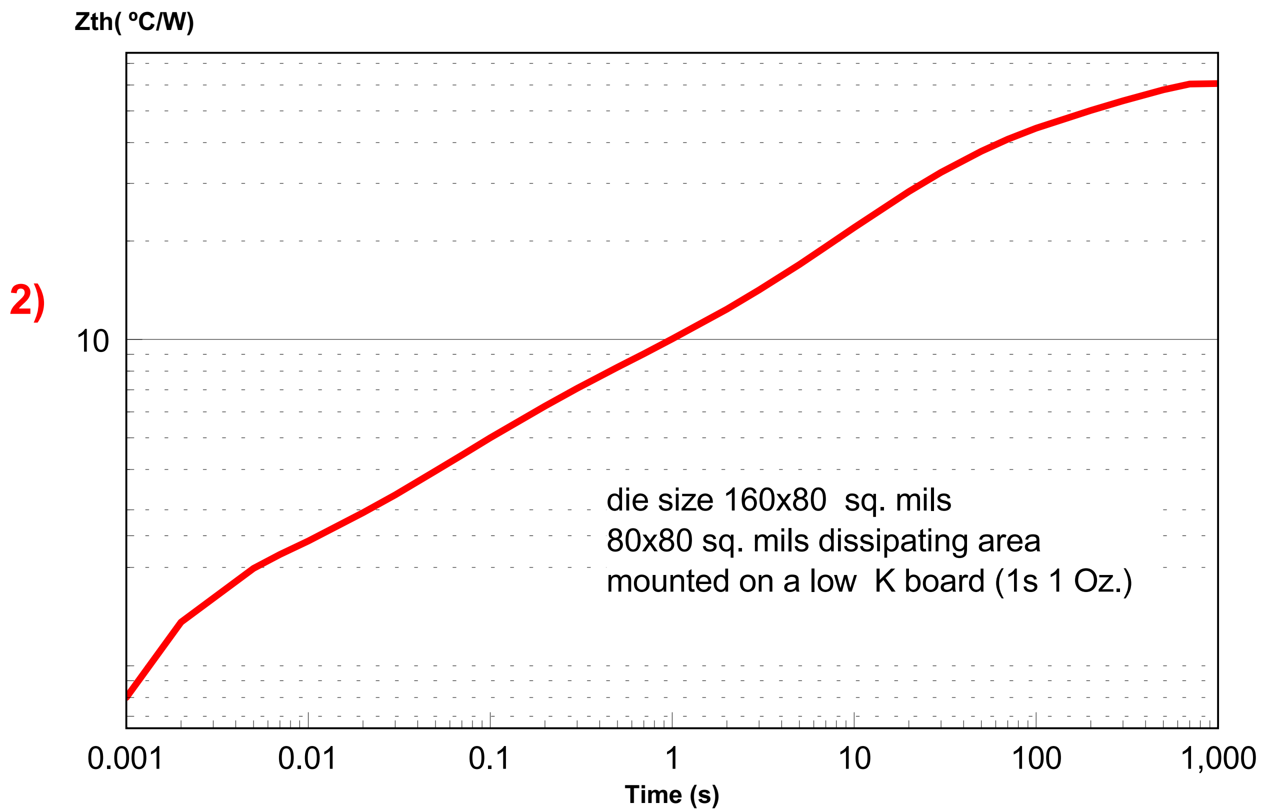
1)



2)



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